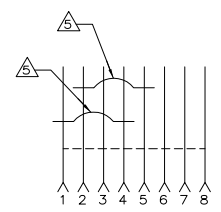
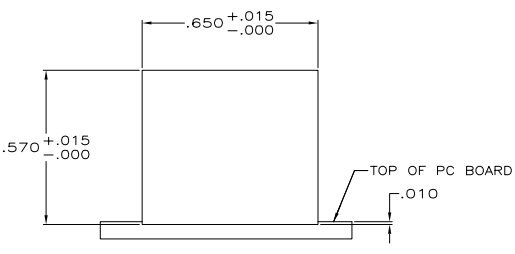
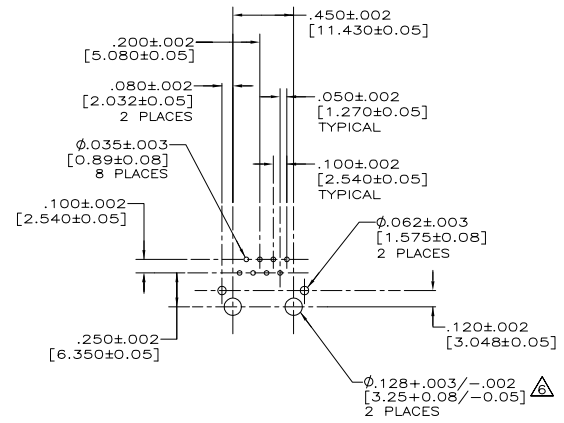
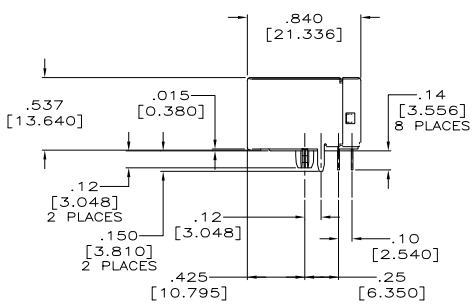
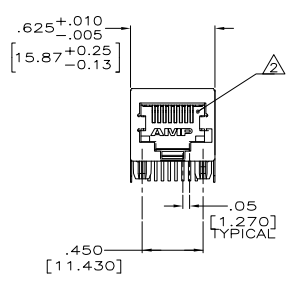


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LOC	DIST	REVISIONS					
AA	22	P	UR	DESCRIPTION	DATE	DR	APPD
		A1		REV PER ECR-09-004284	16APR2009	TY	SY



- ⚠ MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0. TERMINALS - .013[0.33] THICK PHOS BRONZE PLATED WITH .000050[1.27µm] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND .000150 [3.81µm] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER .000050[1.27µm] MINIMUM THICK NICKEL UNDERPLATE. SHIELD: .254mm[.010] THICK COPPER ALLOY PLATED WITH 1.27µm [.000050] MINIMUM NICKEL AND 2.03 µm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- ⚠ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
- 4. ALL DIMENSIONS SHOWN IN BRACKETS [] ARE IN MILLIMETERS.
- ⚠ SHORT IS REMOVED BY INSERTION OF MODULAR PLUG.
- ⚠ USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.

SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE

SUGGESTED PANEL CUTOUT
SCALE 4:1

SHORTING FEATURE

5557789-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DR: G. ATTADIA - DOCKS	DATE: 15JAN2009	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: Inches [mm]		DR: J. WESTMAN	DATE: 15JAN2009	Tyco Electronics	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		DR: S. FLICKINGER	DATE: 15JAN2009	MODULAR JACK ASSEMBLY, 8 POSITION RIGHT ANGLE, LOW PROFILE, SHORTING, SHIELDED, PC BOARD GROUND	
0 P/LC	# -	PRODUCT SPEC	108-1163	SIZE	114-2048
1 P/LC	# -	APPLICATION SPEC	114-2048	DATE CODE (FORMING NO)	A2 00779
2 P/LC	# 010(0.254)			RESTRICTED TO	
3 P/LC	# 205(0.127)				
4 P/LC	# -				
ANGLES	# -				
MATERIAL	FINISH	WEIGHT			
		CUSTOMER DRAWING	SCALE 2:1	SHEET 1 of 1	REV A1